

Amendments to the Claims

Please amend claim 30 as set forth below. In compliance with current amendment practice, all pending claims are reproduced below. Changes in the amended claim are shown by underlining (for added matter) and strikethrough/double brackets (for deleted matter).

1. (Previously Presented) A structure comprising:

a first substrate and a second substrate; and

first reflowed solder bumps and second reflowed solder bumps offset therebetween, wherein said first reflowed solder bumps and said second reflowed solder bumps are separate solder bumps disposed between said first substrate and said second substrate, and wherein said second reflowed solder bumps have at least a portion that melts at a lower temperature than said first reflowed solder bumps; and

wherein said second reflowed solder bumps comprise alignment solder bumps which aligned said first reflowed solder bumps between said first substrate and said second substrate before said first reflowed solder bumps were reflowed.
2. (Original) A structure as recited in claim 1, wherein said second solder bumps are larger than said first solder bumps.
3. (Original) A structure as recited in claim 1, wherein said second solder bumps comprise a portion having a higher concentration of tin than does said first solder bumps.
4. (Original) A structure as recited in claim 3, wherein said portion comprises a eutectic concentration of tin.
5. (Original) A structure as recited in claim 3, wherein said portion is adjacent to said second substrate.
6. (Original) A structure as recited in claim 3, wherein said portion is centrally located within said second solder bump.

7. (Original) A structure as recited in claim 3, wherein said portion is said entire second solder bumps.

8-9. (Canceled)

10. (Original) A structure as recited in claim 1, wherein said second solder bumps melt at a temperature at least 25C less than said first solder bumps.

11. (Original) A structure as recited in claim 1, wherein said first substrate comprises a first semiconductor chip.

12. (Original) A structure as recited in claim 11, wherein said second substrate comprises a second semiconductor chip.

13. (Original) A structure as recited in claim 12, wherein said second chip is larger than said first chip.

14. (Original) A structure as recited in claim 12, wherein said second chip further comprises wire bond pads for bonding to a printed circuit board.

15-29. (Canceled)

30. (Currently Amended) A structure comprising:

a first substrate having a main surface with first reflowed solder bumps and second reflowed solder bumps separately disposed thereacross; and

wherein said second reflowed solder bumps have at least a portion that ~~[[melts]]~~ melted at a lower temperature than said first reflowed solder bumps, said second reflowed solder bumps comprising alignment solder bumps which when melted ~~[[align]]~~ aligned said first substrate to a second substrate before melting said first reflowed solder bumps.

31. (Presently Presented) The structure of claim 30, wherein said second solder bumps are larger than said first solder bumps.

32. (Presently Presented) The structure of claim 30, wherein said second solder bumps melt at a temperature at least 25°C less than said first solder bumps.

33. (Presently Presented) The structure of claim 32, wherein the first substrate comprises a semiconductor chip.

34. (Presently Presented) The structure of claim 1, wherein said second solder bumps have a uniform composition and melt at a lower temperature than said first solder bumps.

35. (Presently Presented) The structure of claim 30, wherein said second solder bumps have a uniform composition and melt at a lower temperature than said first solder bumps.

* * * * *